

IN THE CLAIMS:

1 1. (previously presented) A die containing package comprising:
2 a die defining electrical die contacts, the die contacts arranged along a first and an
3 opposite side of the die,
4 a substrate defining first substrate contacts,
5 flattened electrical conductive balls attached to the die contacts and making electri-
6 cal connection thereto,
7 electrical conductive runs on the substrate that run substantially under the die con-
8 necting the first substrate contacts, wherein the first substrate contacts are located adjacent
9 to the first side of the die, to second substrate contacts, wherein the second substrate con-
10 tacts are located adjacent to the opposite side of the die, electrically conductive wires with
11 first ends making electrical connections to the first substrate contacts, wherein the wires
12 are formed to run substantially parallel to the surface of the die, and wherein the other ends
13 are horizontally attached to the flattened balls.

1 2-3. canceled.

1 4. (previously presented) The die containing package of claim 1 wherein the second sub-
2 strate contacts are located on the substrate to accommodate a pin out different from the die.

1 5. (previously presented) A process for packaging a die comprising the steps of:
2 defining electrical die contacts, the electrical die contacts arranged along a first and
3 an opposite side of the die,
4 defining a substrate with first substrate contacts,
5 flattening electrical conductive balls,
6 attaching the flattened electrically conductive balls to the die contacts,

7 forming electrical conductive runs on the substrate that run substantially under the
8 die connecting the first substrate contacts, wherein the first substrate contacts are located
9 adjacent to the first side of the die, to second substrate contacts, wherein the second sub-
10 strate contacts are located adjacent to the opposite side of the die,
11 connecting electrically conductive wires to the first substrate contacts,
12 running the electrically conductive wires substantially parallel to the surface of the
13 die to the die contacts, and
14 horizontally attaching the other ends of the wires to the flattened electrical conductive balls
15 thereby making electrical connections therebetween, and wherein the other ends remain
16 substantially parallel to the surface of the die .

1 6-7. canceled.

1 8. (previously presented) The process of claim 5 further comprising the step of locating
2 the second substrate contacts on the substrate to accommodate a pin out different from
3 the die.